



**SNS COLLEGE OF TECHNOLOGY**  
**Coimbatore-35**  
**An Autonomous Institution**



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**DEPARTMENT OF ELECTRONICS & COMMUNICATION ENGINEERING**

**23ECB101 – CIRCUIT ANALYSIS AND DEVICES**

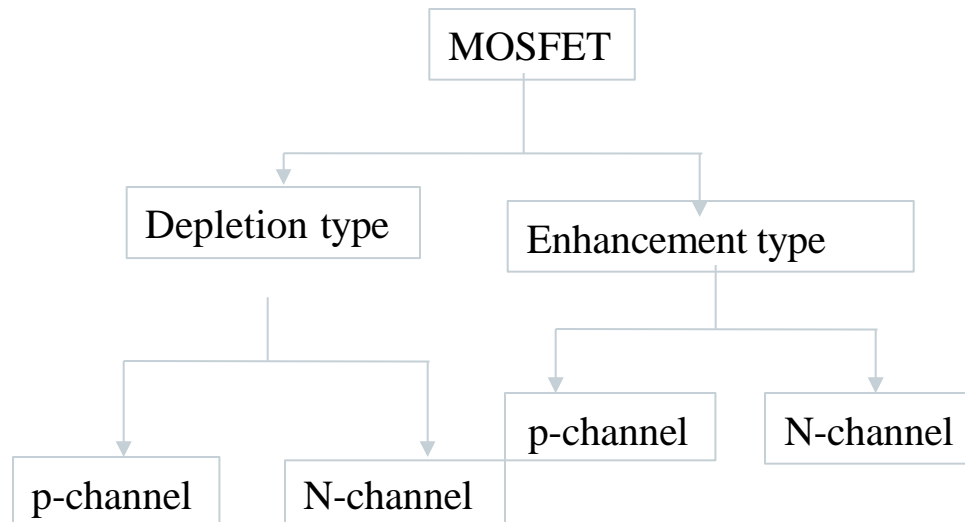
I YEAR/ II SEMESTER

**UNIT 4 – TRANSISTORS AND THEIR APPLICATIONS**

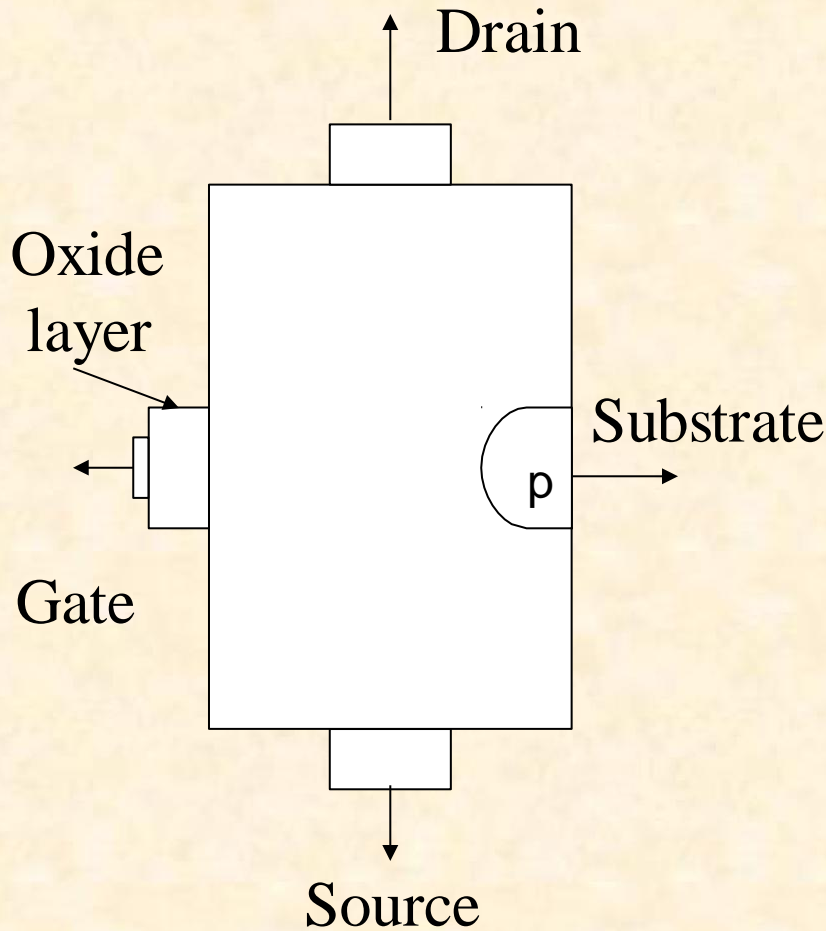
**TOPIC - MOSFET**



# Classification of MOSFETs



# Metal oxide semiconductor field effect transistor (MOSFET)

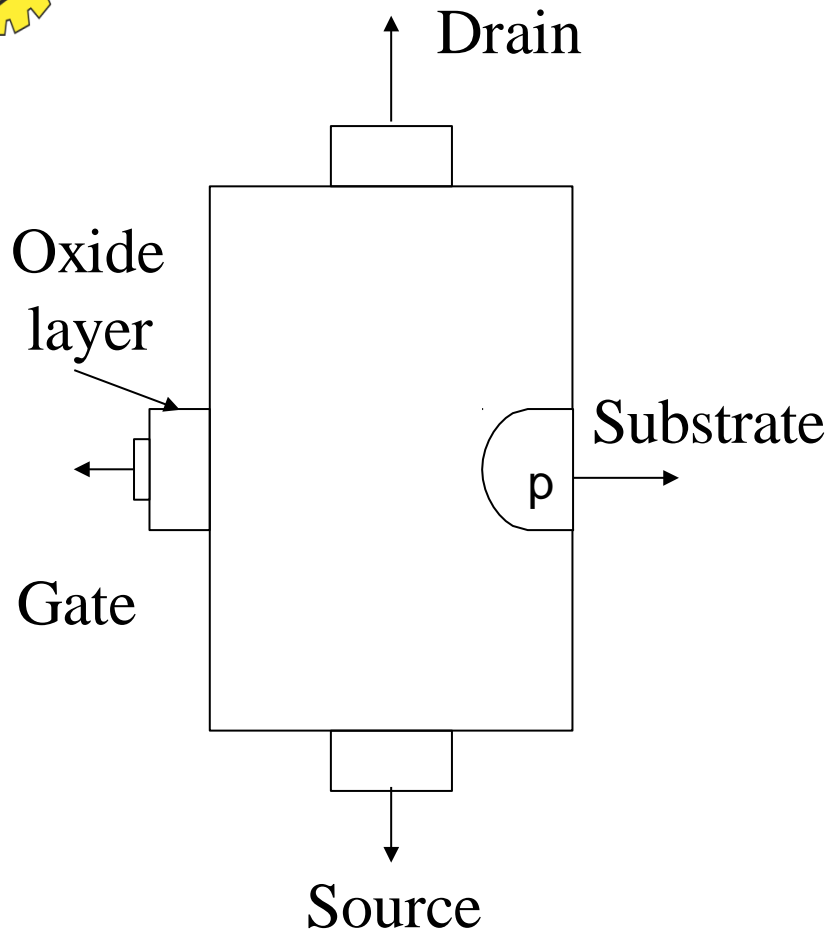


**N Channel**

- MOSFET is an important semiconductor device and is widely used in many circuit application.
- The input impedance of a MOSFET is much more than that of a FET because of very small leakage current.
- MOSFETs have much greater commercial importance than JFET



# MOSFET (contd)



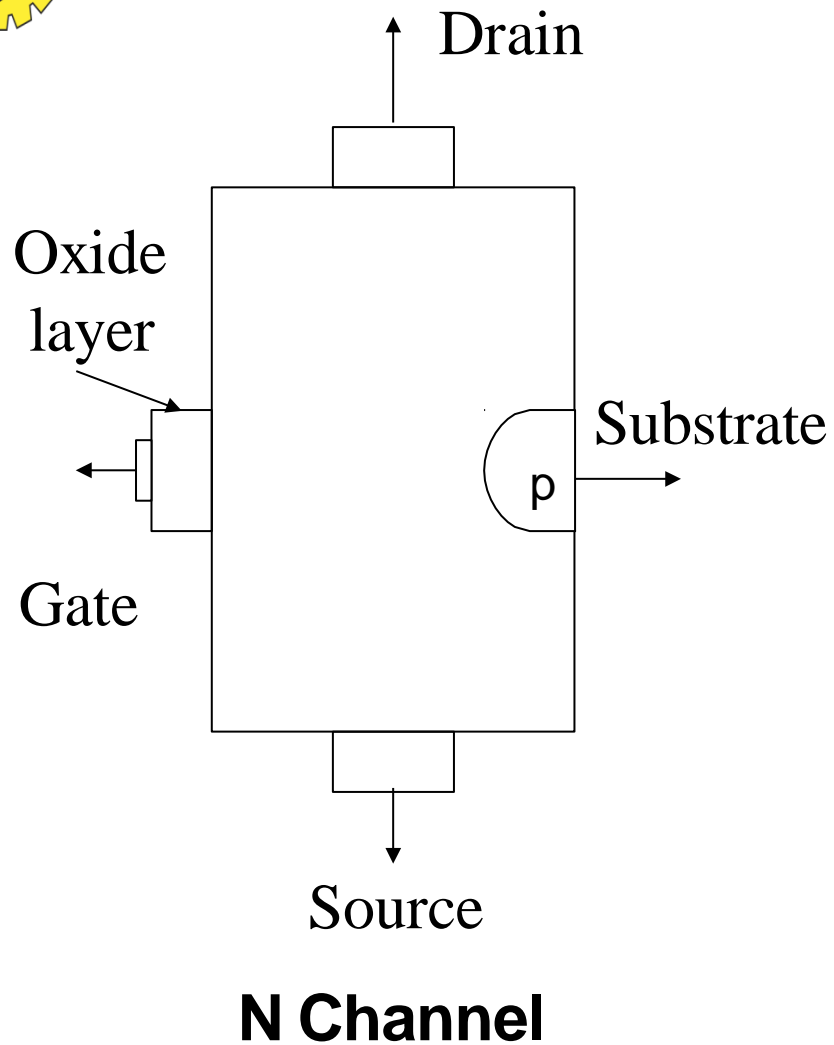
**N Channel**

- The MOSFET can be used in any of the circuits covered for the FET.

- Therefore all the equations apply equally well to the MOSFET and FET in amplifier connections.



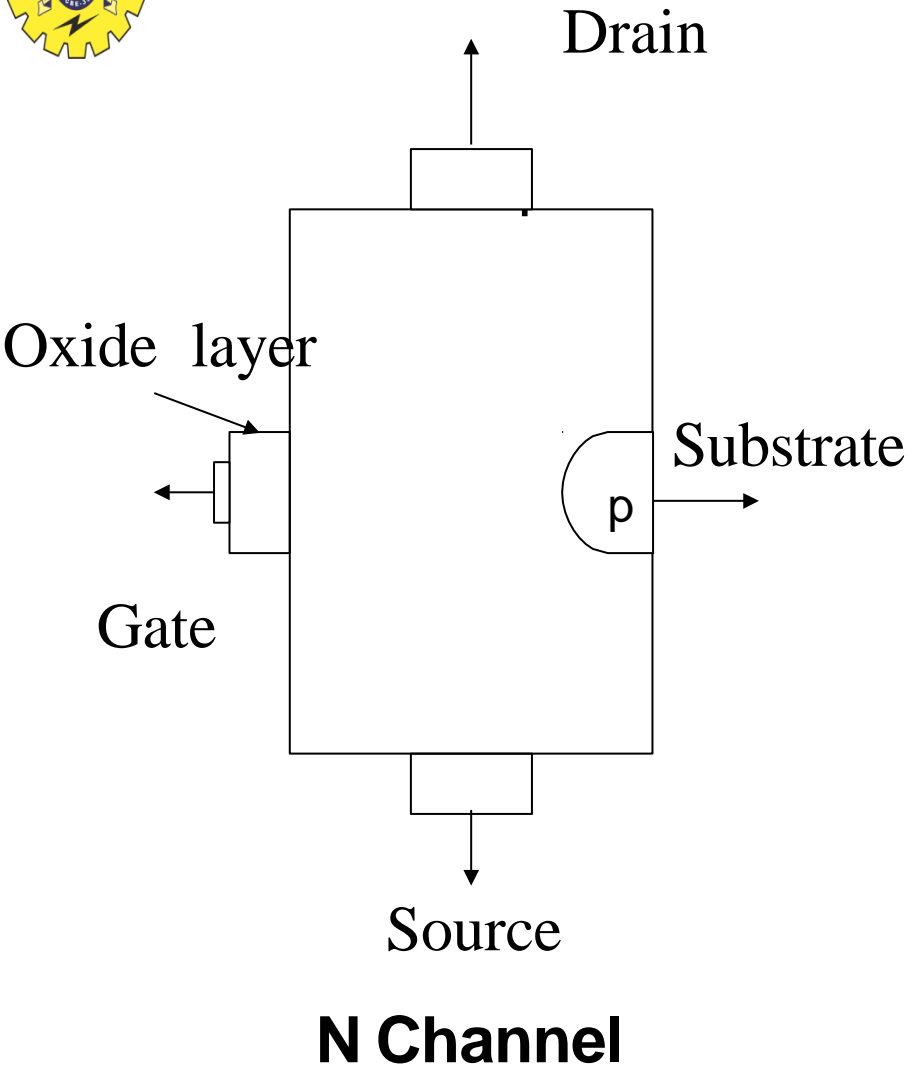
# MOSFET (contd)



- MOSFETs uses a metal gate electrode (instead of p-n junction in JFET), separated from the semiconductor by an insulating thin layer  $\text{SiO}_2$  to modulate the resistance of the conduction channel.



# MOSFET (contd)

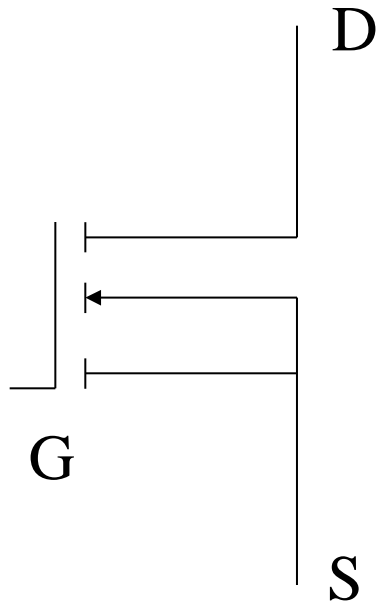


It is also called as insulated gate FET (IGFET)

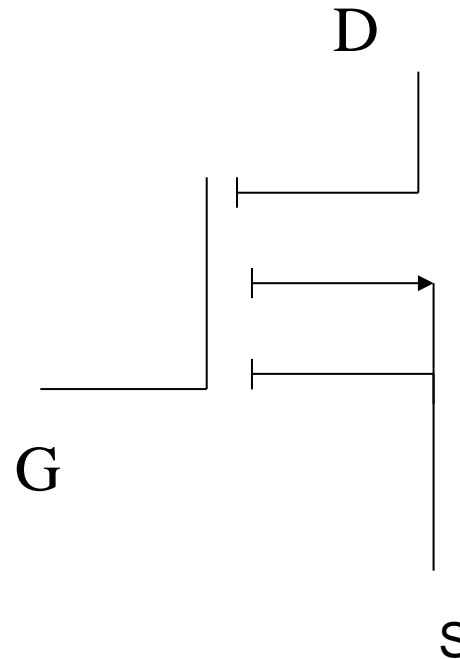
MOSFETs operates both in the depletion mode as well as in the enhancement mode



# CIRCUIT SYMBOLS OF MOSFET



N channel



P channel



# Differences between MOSFET and FET

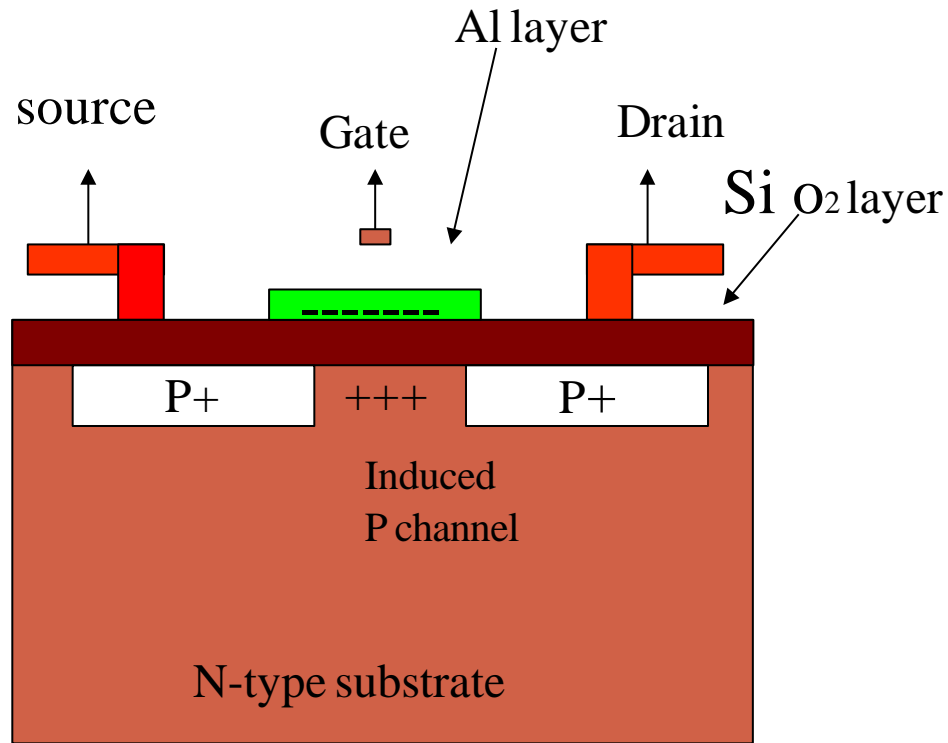


- There is only a single  $p$ -region. This is called *substrate*.
- A thin layer of metal oxide is deposited over the left side of the channel. A metallic gate is deposited over the oxide layer. As silicon dioxide is an insulator, therefore a gate is insulated from the channel. For this reason MOSFET is some times called insulated gate FET.





# ENHANCEMENT MOSFET

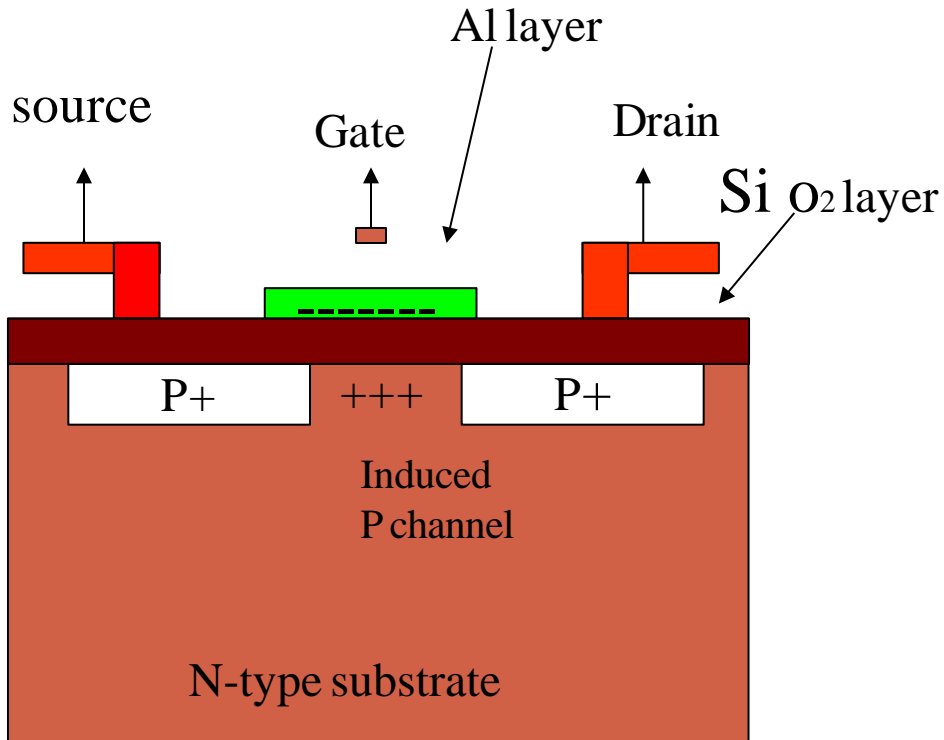


- A p-channel MOSFET consists of lightly doped n-substrate into which two heavily doped p<sup>+</sup> regions act as the source and the drain.
- A thin layer of SiO<sub>2</sub> is grown over the surface of the entire assembly..

## *P channel Enhancement MOSFET*



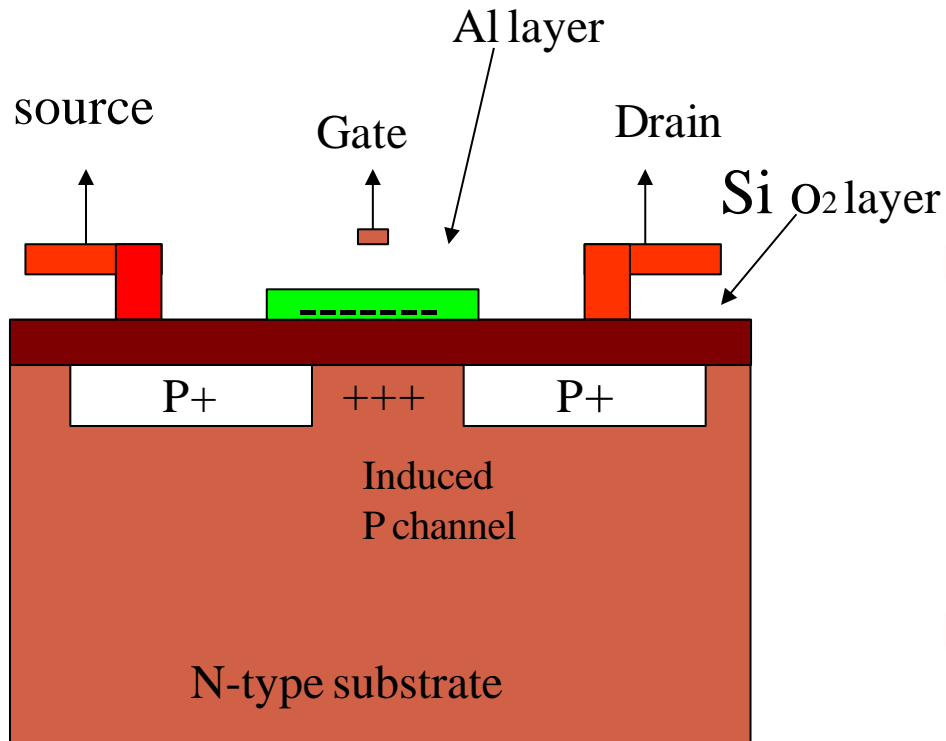
# Construction



- Holes are cut into this SiO<sub>2</sub> layer for making contact with p+ source and drain regions.
- On the SiO<sub>2</sub> layer, a metal (aluminium) layer is overlaid covering the entire channel region from source to drain.
- This aluminum layer constitutes the gate.

## *P channel Enhancement MOSFET*

# Construction



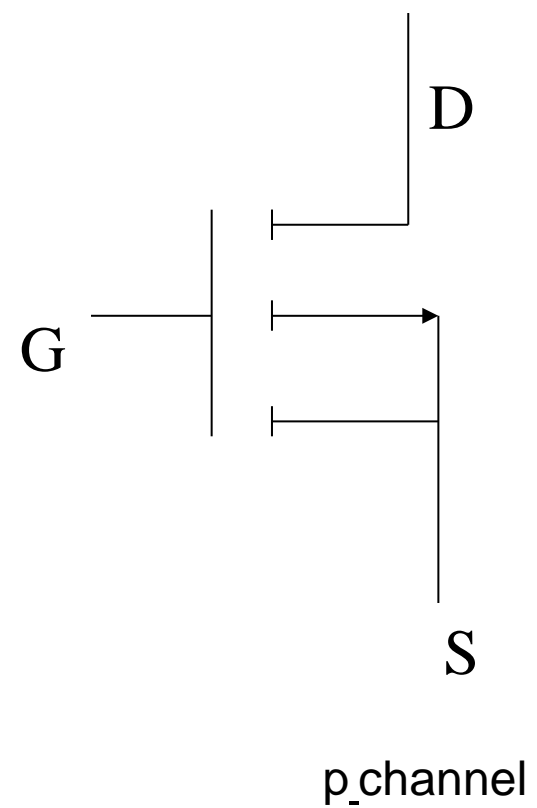
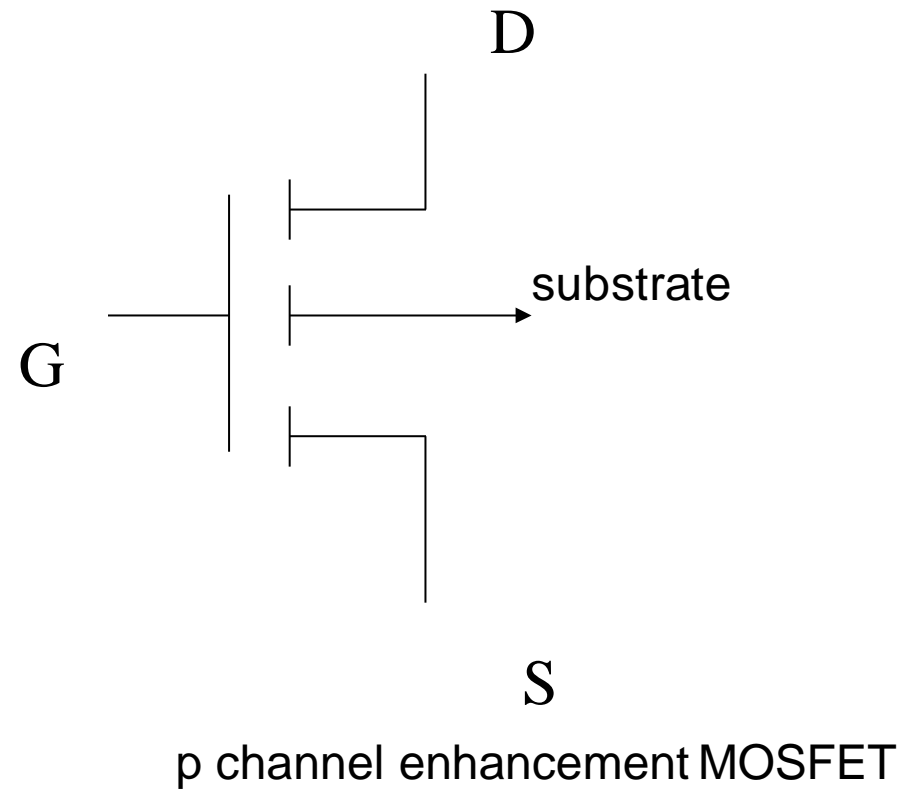
## *P* channel Enhancement MOSFET

- The area of MOSFET is typically 5 square mills or less.
- This area is extremely small being only about 5% of the area required for a bipolar junction transistor.
- A parallel plate capacitor is formed with the metal areas of the gate and the semiconductor channel acting as the electrodes of the capacitor.
- The oxide layer acts as the dielectric between the electrodes.



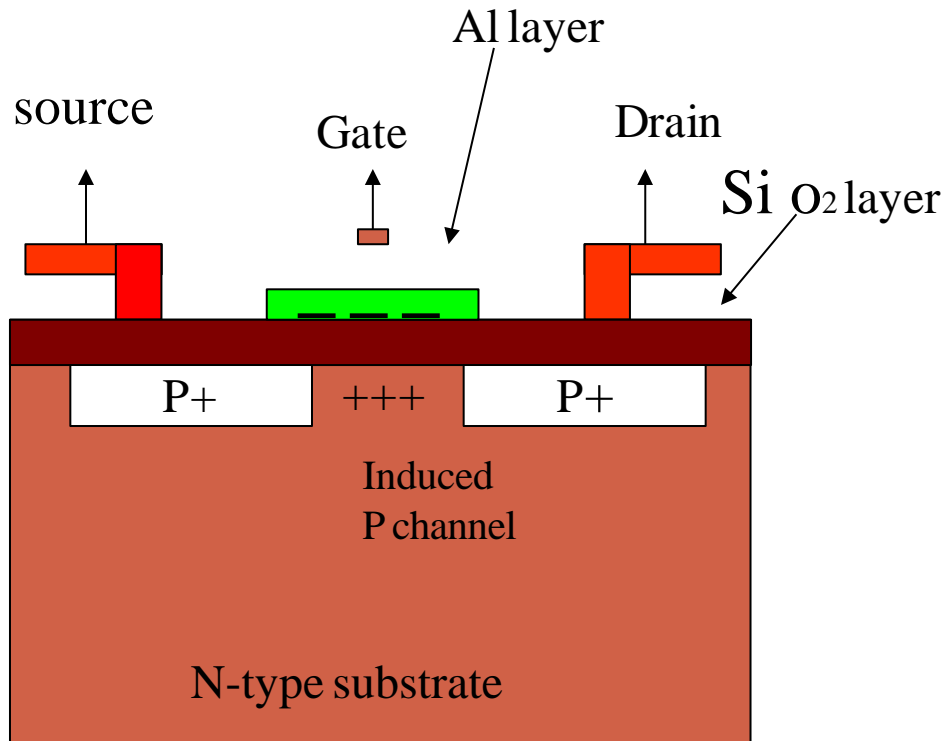


# symbols





WORKING

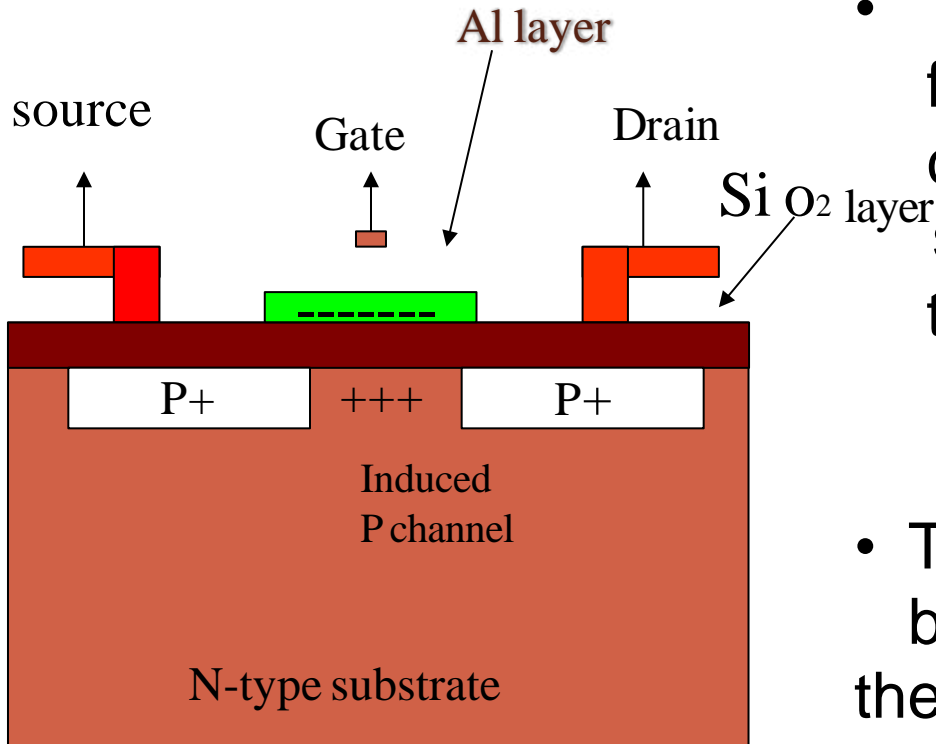


## P channel Enhancement MOSFET

- The substrate will be connected to the common terminal i.e., to the ground terminal.
- A negative potential will be applied to the gate.
- This results in the formation of an electric field normal the  $\text{SiO}_2$  layer.



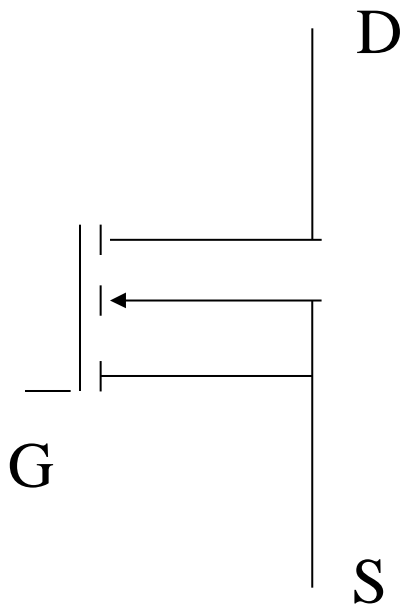
# WORKING



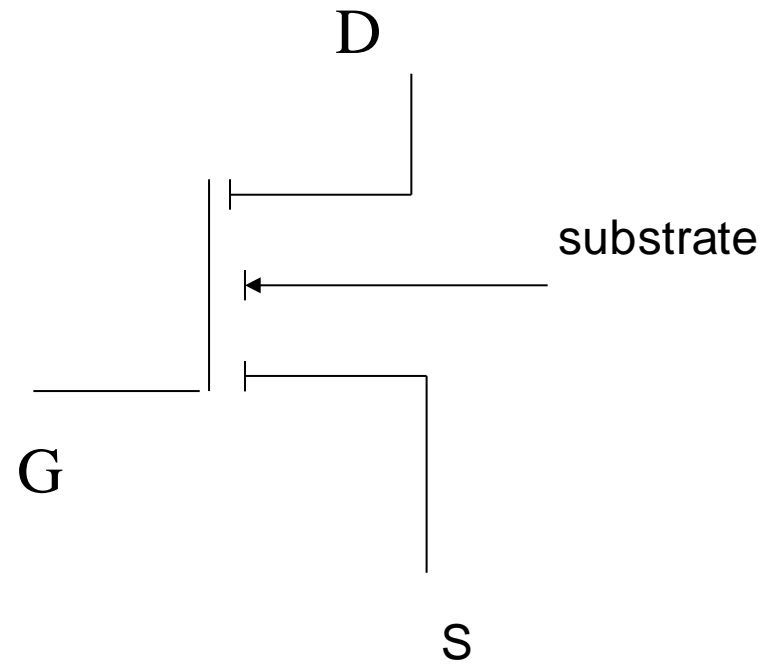
- This electric field originates from the induced positive charges on the semiconductor side on the lower surface of the SiO<sub>2</sub> layer.
- The induced positive charge become minority carriers in the n-type of substrate.

## *P channel Enhancement MOSFET*

# Enhancement MOSFET symbols

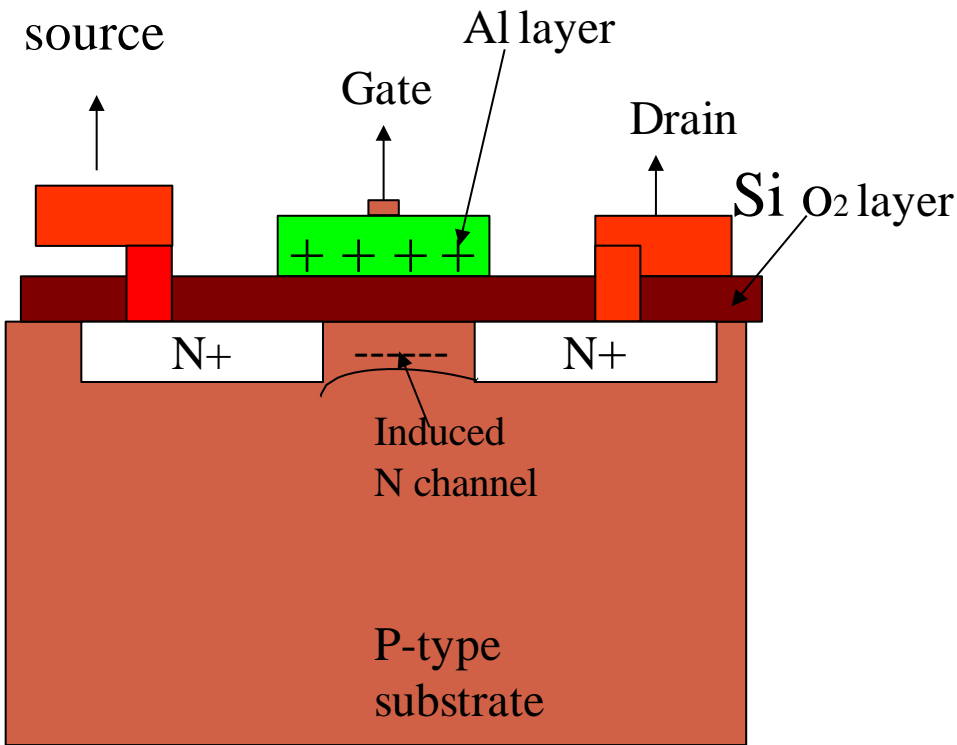


N channel



P channel

# WORKING



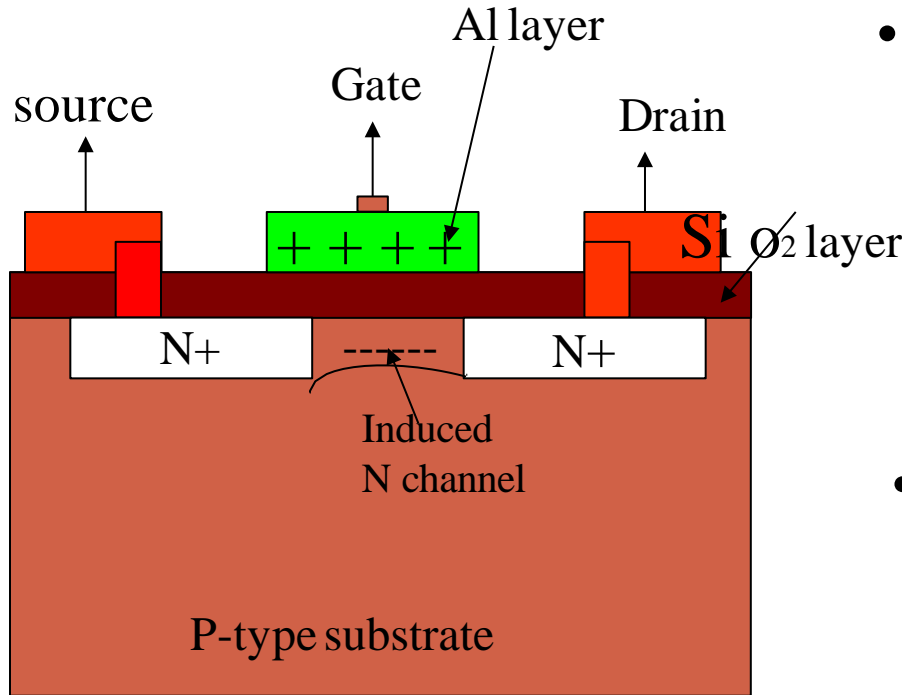
## N channel Enhancement MOSFET

- It consists of a lightly doped p type substrate in to which two heavily Doped n type material are diffused.
- The surface is coated with a layer of silicon dioxide(SiO<sub>2</sub>).
- Holes are cut through the SiO<sub>2</sub> to make contact with n-type blocks.





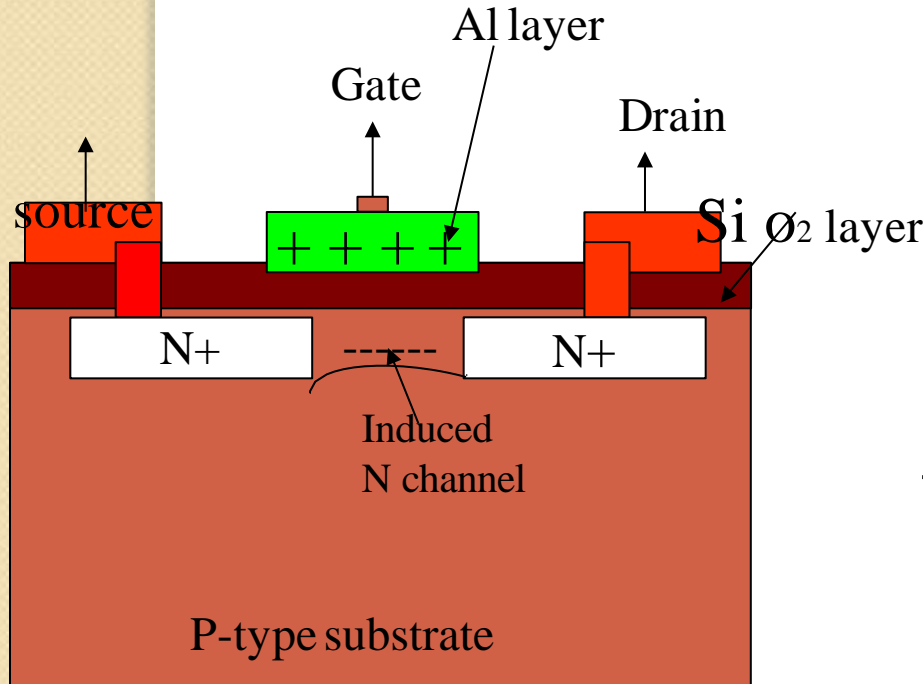
# WORKING



- Metal (Al) is deposited through the Holes to form drain and source terminals

- The surface area between drain and source a metal plate is deposited from which gate terminal is taken out.

## N channel Enhancement MOSFET

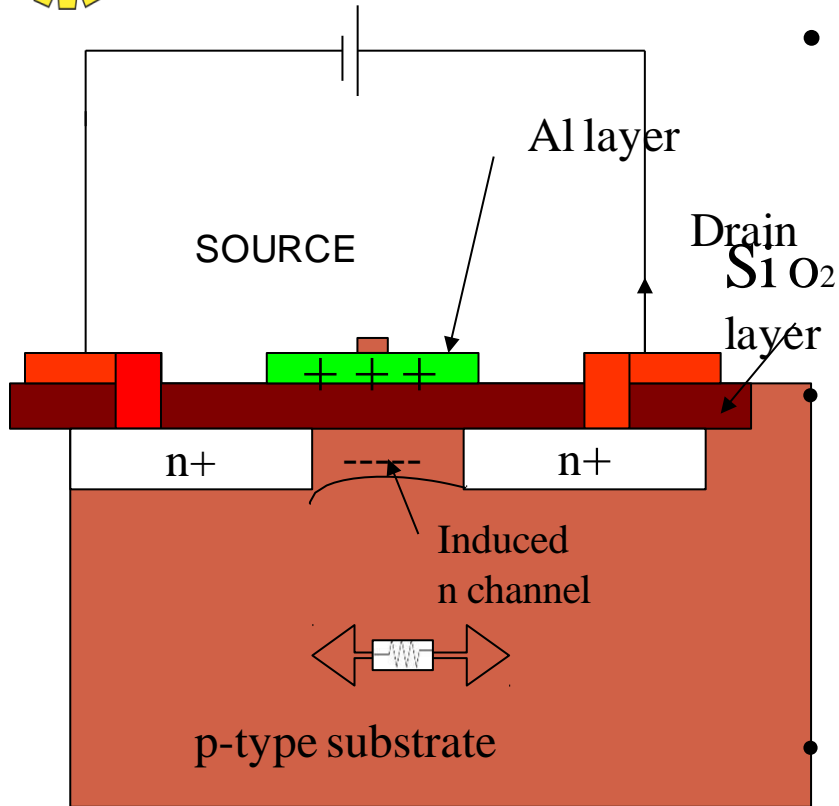


## N channel Enhancement MOSFET

- Gate is insulated from the body of FET so it is called insulated gate FET(IGFET).
- Structurally there exists no channel between source and drain so MOSFET some times called as N-channel enhancement type
- Because a thin layer of P-type substrate touching the metal oxide film provides channel for electrons and hence acts like N-type material.



# WORKING OF THE ENHANCEMENT MOSFET

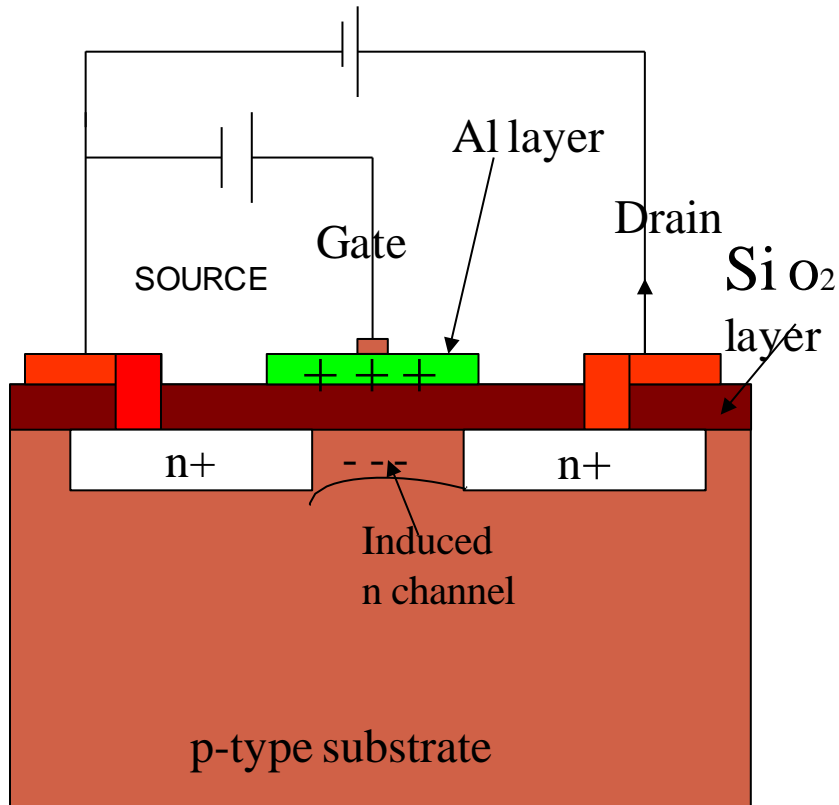


## ***n channel Enhancement MOSFET***

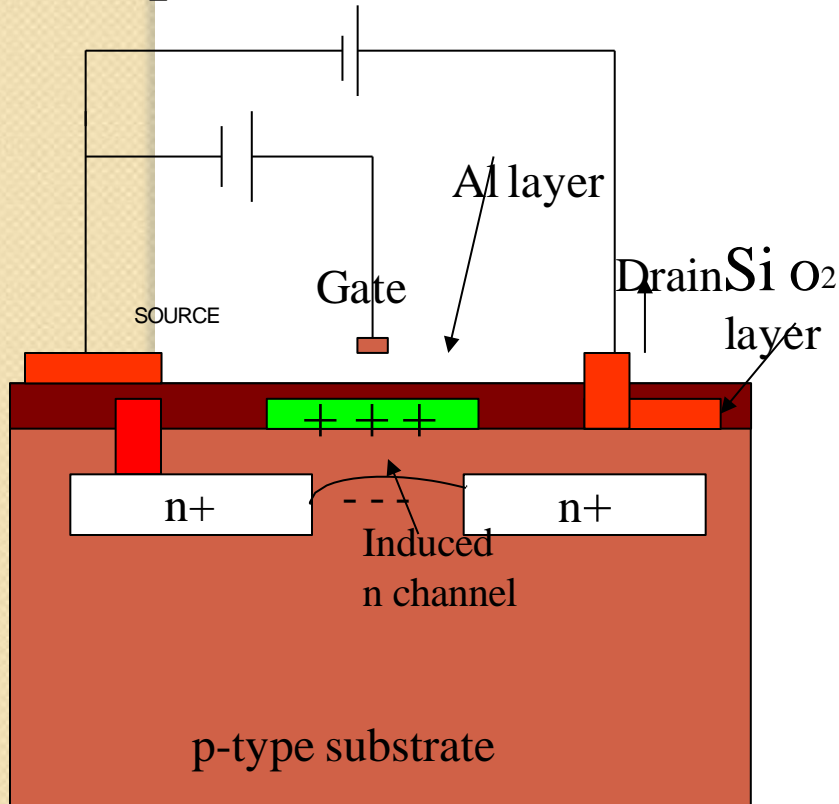
- Drain is made positive with respect to the source and no potential is applied to the gate as shown in figure.

The two n-blocks and p-type substrate form back to back pn junctions connected by the Resistance of the p-type material.

- Both the junctions cannot be forwarded at the Same time so small drain current order of few nano amperes flows.



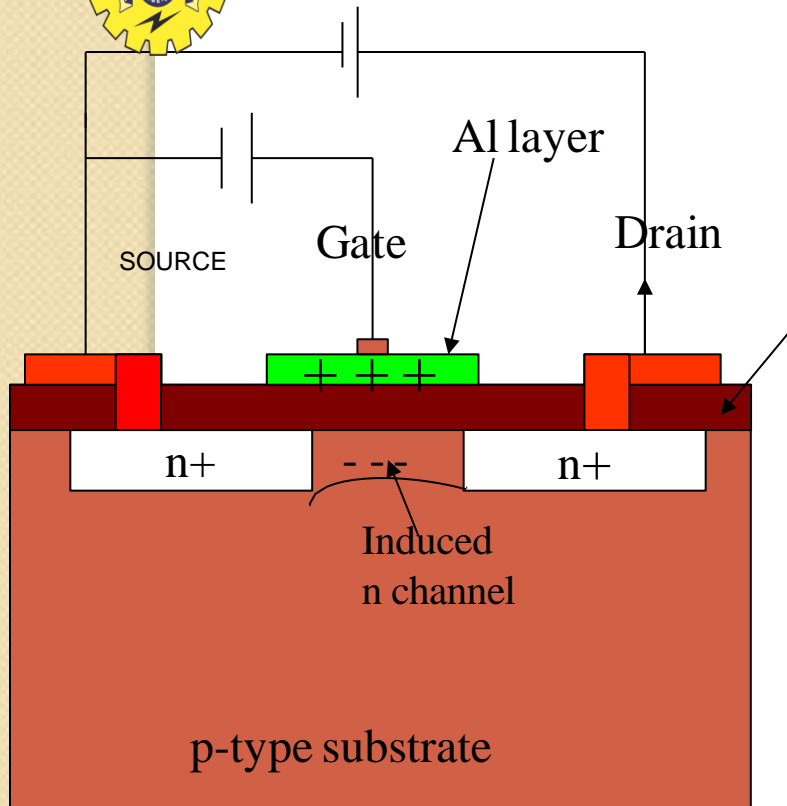
- So MOSFET is cut off when gate source voltage is zero.
- That is why it is called normally-OFF MOSFET.
- The gate is made positive with respect to source substrate as shown in figure.
- A channel of electrons (n-channel) is formed in between the source and drain regions.



- Behaves as a capacitor with gate metal acting as one electrode, upper surface of the substrate as other electrode and  $\text{SiO}_2$  layer as dielectric medium.

- When positive voltage is applied to gate the capacitor begin to charge.

### *N channel Enhancement MOSFET*



*N channel Enhancement MOSFET*

- Consequently positive charges appears on the gate and negative charges appears

in the substrate between the drain and source.

- The n-channel thus formed is called induced n-channel or n-type inversion layer.

- As  $V_{GS} \uparrow$ , no. electrons in the channel  $\uparrow$ ,  $I_D \uparrow$ .

- The minimum gate source voltage which produces the induced n-channel is called threshold voltage  $V_{GS(th)}$  when  $V_{GS} < V_{GS(th)}$ ,  $I_D = 0$ .



- Drain current starts only  $V_{GS} > V_{GS(th)}$ .
- For a given value of  $V_{DS}$  as  $V_{GS}$  is increased, more and more electrons accumulate under the gate and  $I_D$  increases.



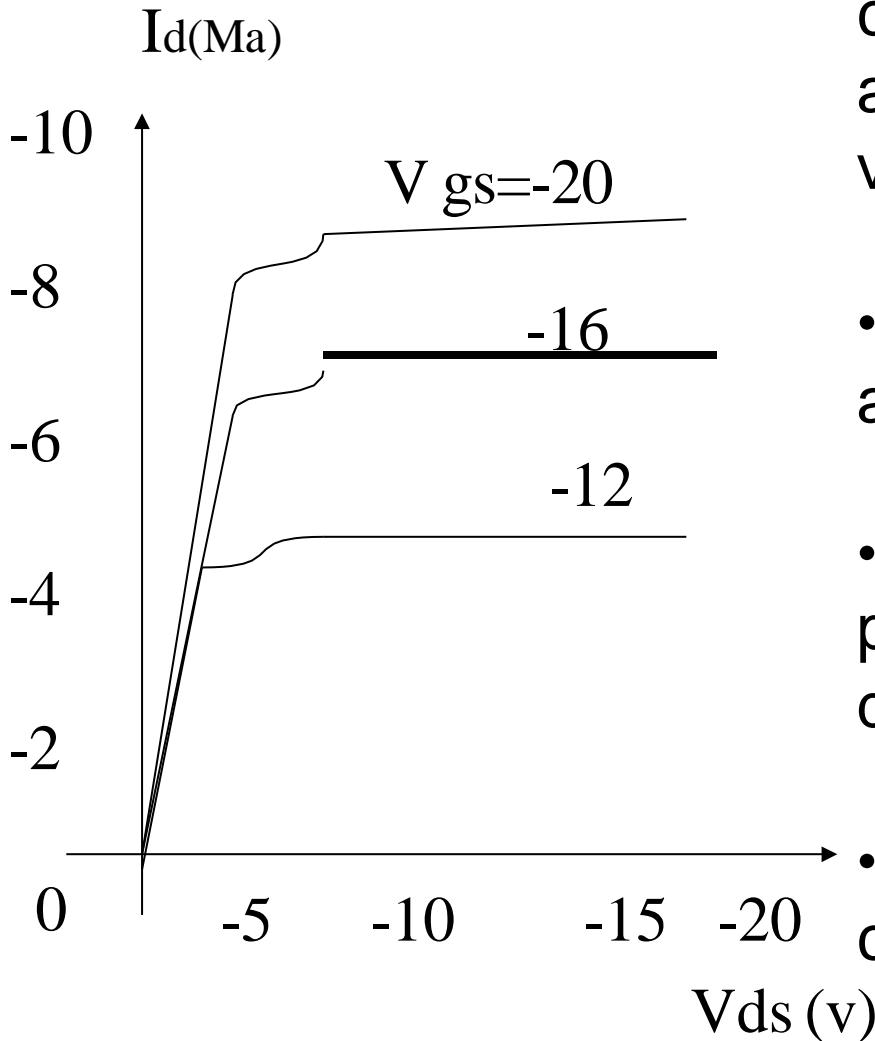
So the conductivity of the channel is enhanced by the positive bias on the gate, the device is known as enhancement mode MOSFET.

- The n-channel MOSFET can never operate with a negative gate voltage.





- Drain characteristics



- It is observed that the drain current has been enhanced on application of negative gate voltage.

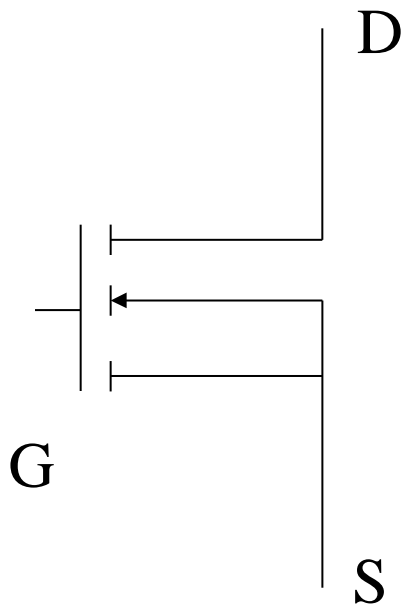
- This is the reason for calling it as enhancement MOSFET.

- By increasing the gate potential, pinch off voltage and drain currents are increased.

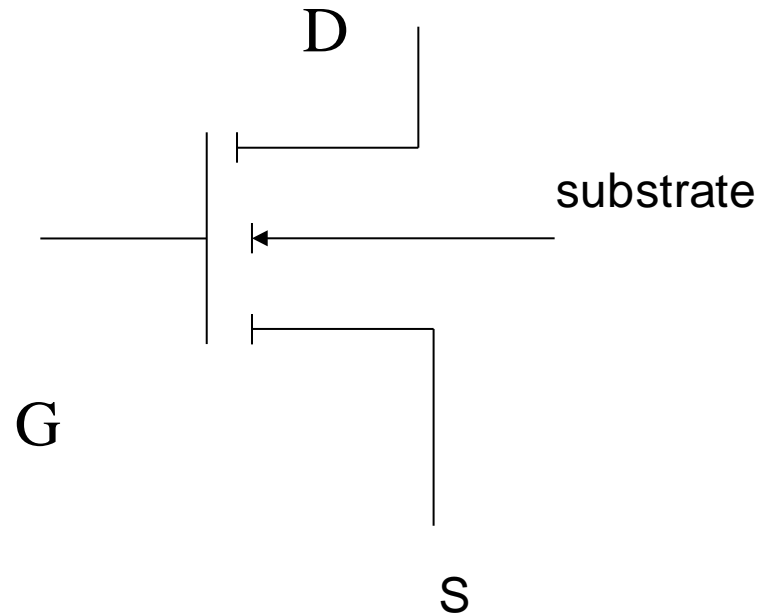
- The curves are similar to drain characteristics of JFET.



# ENHANCEMENT MOSFET



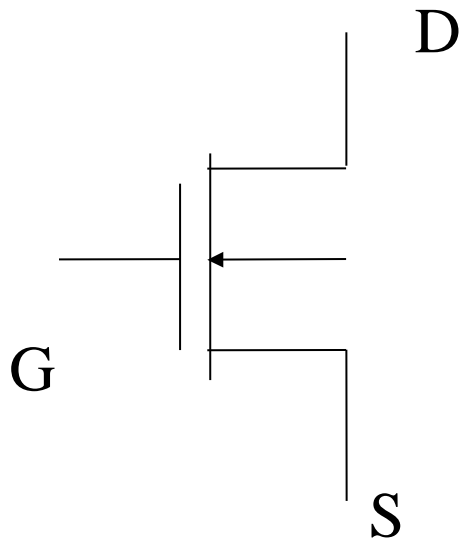
N channel



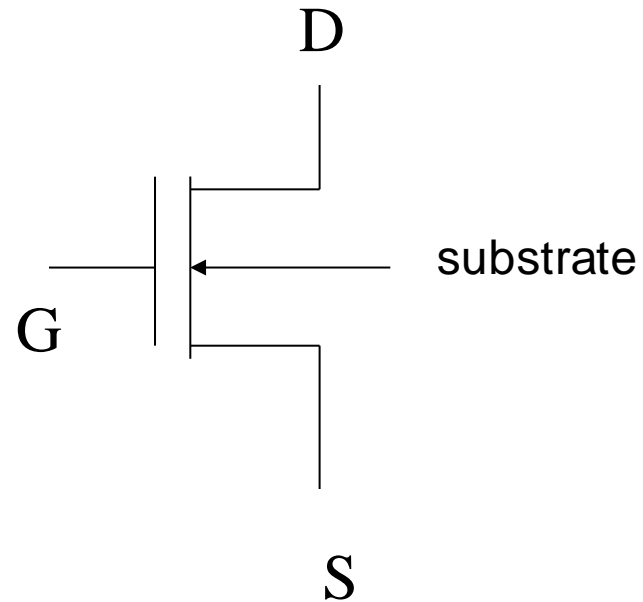
N channel



# DEPLETION MOSFET

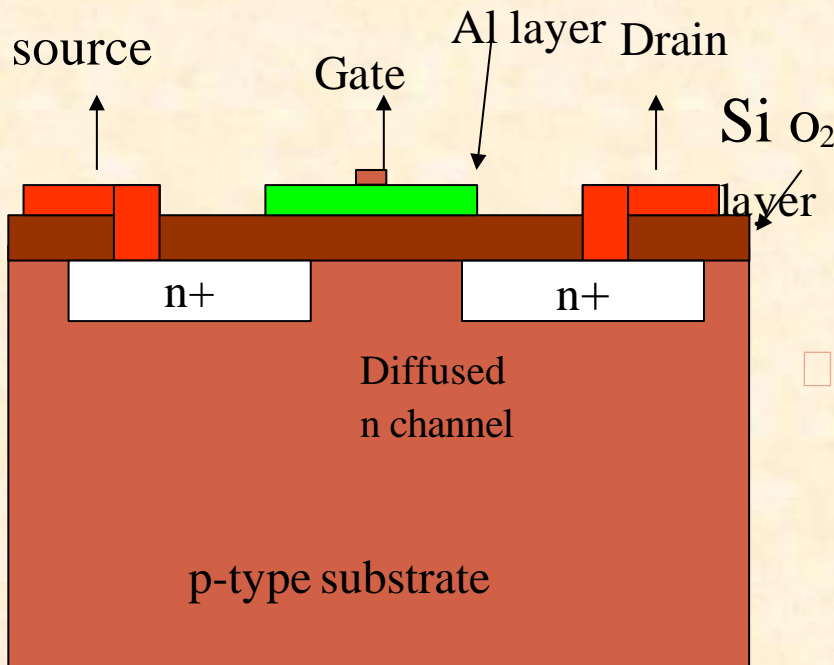


N channel



N channel

# CONSTRUCTION

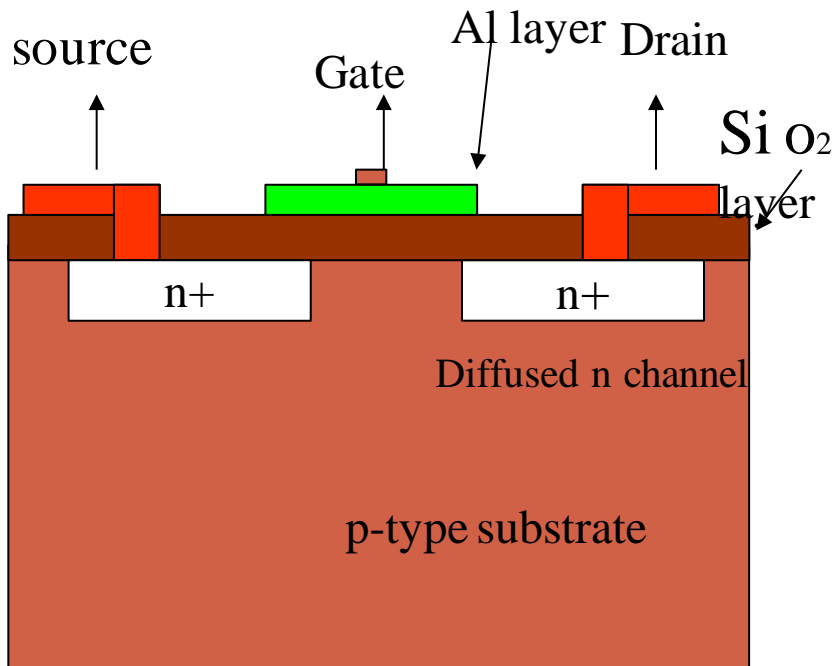


□ Depletion MOSFET may be fabricated from the basic MOSFET structure.

□ An n-type channel is obtained by diffusion between N<sup>+</sup> type source and drain in an n-channel MOSFET.

## N channel Depletion MOSFET

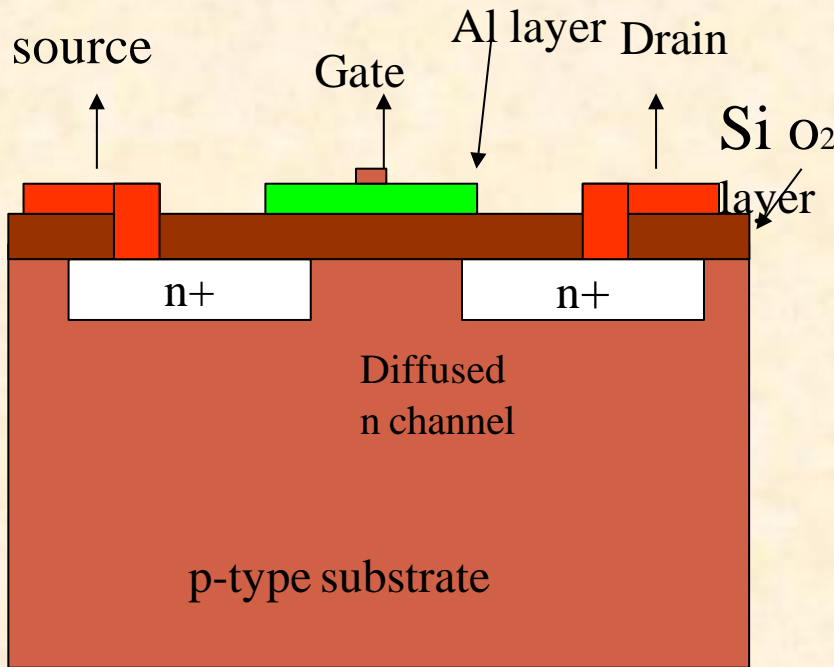
# CONSTRUCTION



## N channel Depletion MOSFET

- In depletion MOSFET a lightly doped n-type channel has been introduced between to heavily doped source & drain blocks,.

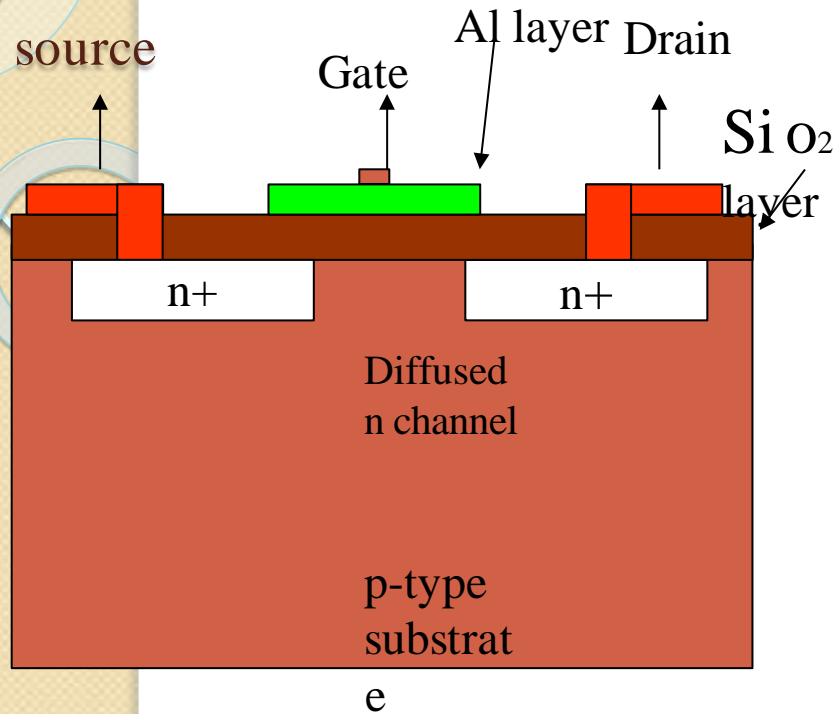
# CONSTRUCTION OF P CHANNEL DEPLETION MOSFET



- Depletion MOSFET may be fabricated from the basic MOSFET structure.

- An p-type channel is obtained by diffusion between p+ type source and drain in an p-channel MOSFET.

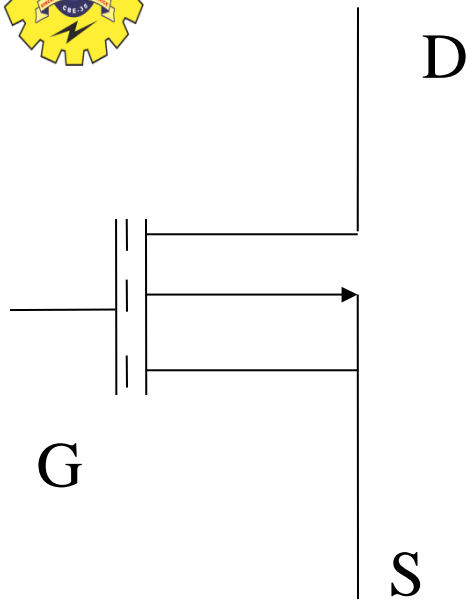
## P channel Depletion MOSFET



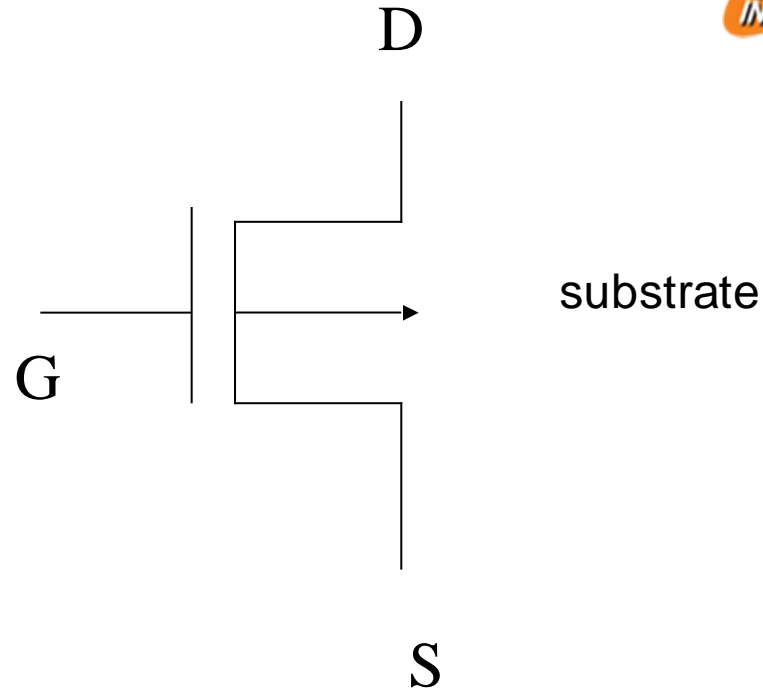
- In p-channel depletion MOSFETs are made by using n-type substrate and diffusing a lightly doped p-type channel between two heavily doped P-type source & drain blocks

## P channel Depletion MOSFET

# Symbols of p channel depletion MOSFET



P channel

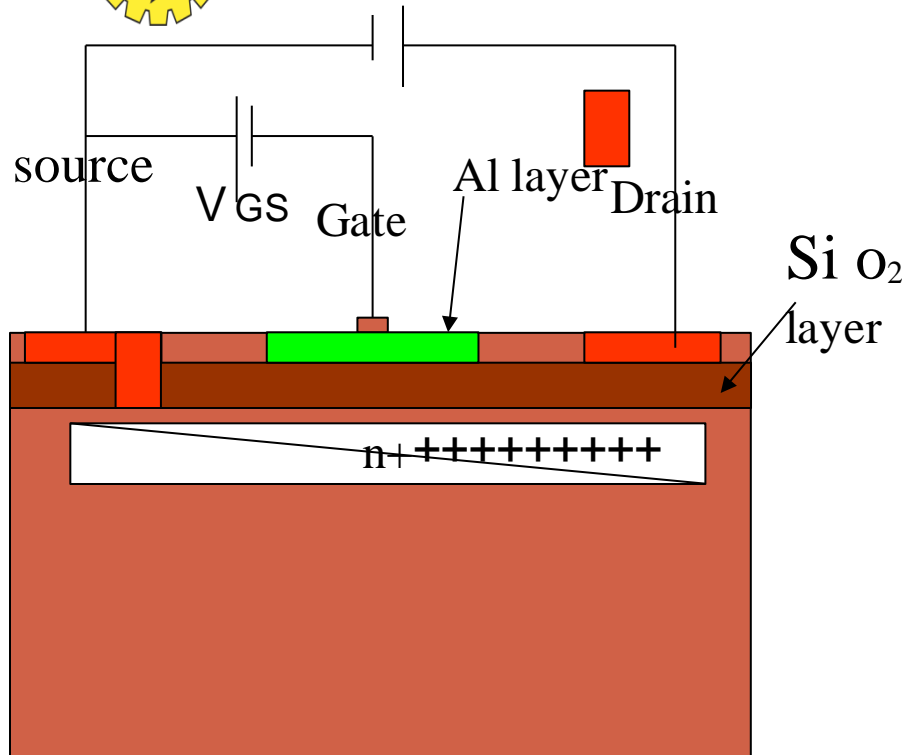


P channel





# Working



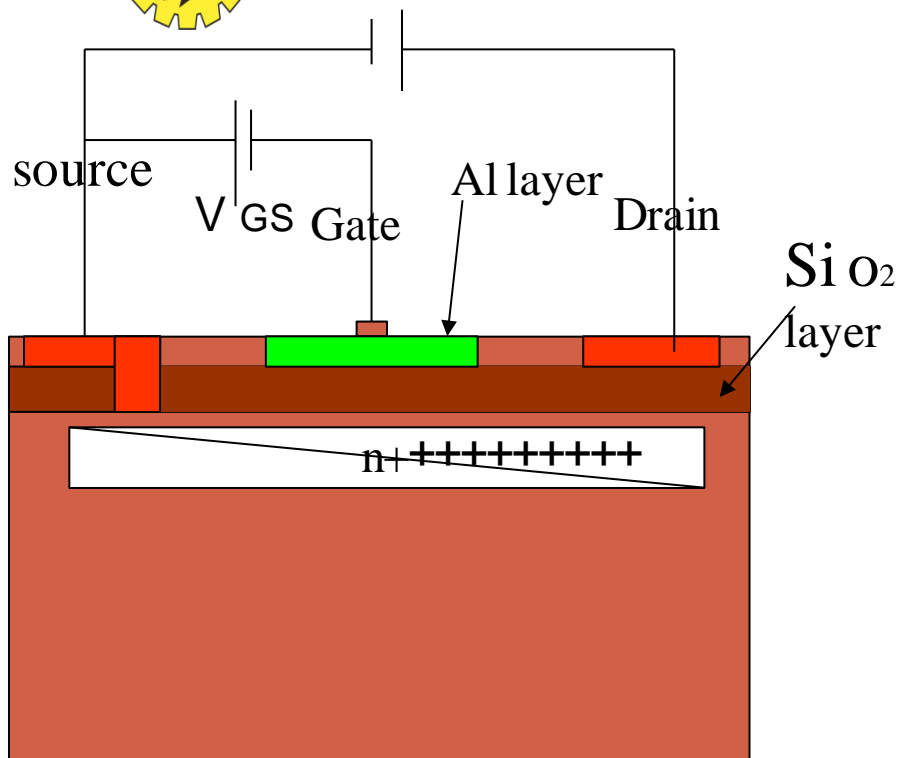
## N channel Depletion MOSFET

- Negative gate operation of a depletion MOSFET is called Its depletion mode Operation
- When  $V_{gs} = 0$  electrons can flow freely from source to drain through the conducting channel. since a channel exists between drain & source,  $I_d$  flows even when  $V_{gs} = 0$ .
- It is also known as normally – ON MOSFET





# Working



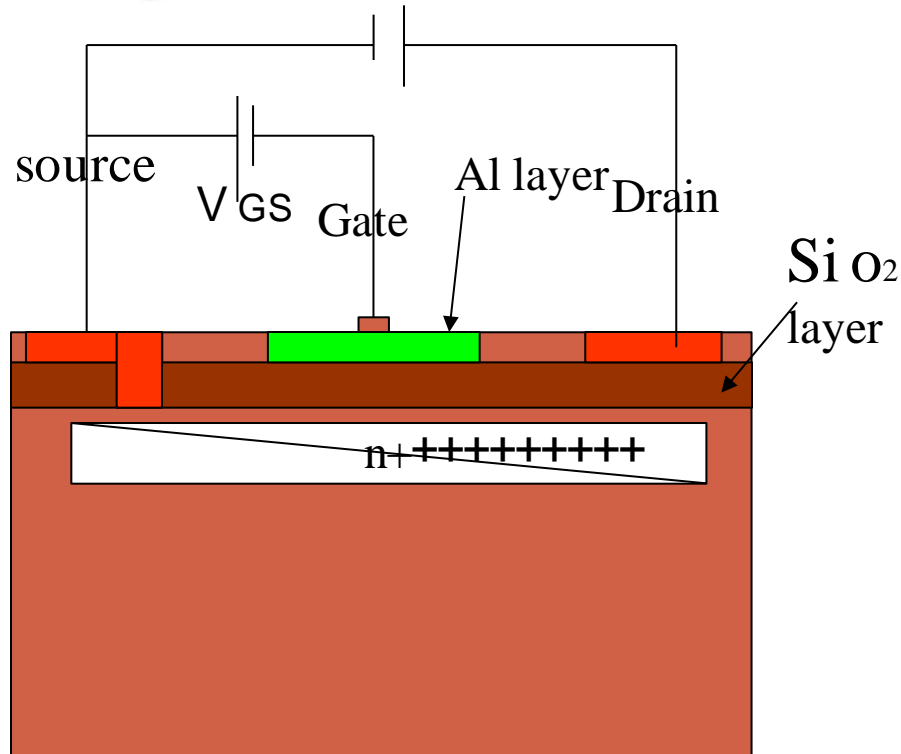
When negative voltage is applied to the gate as shown in Fig positive charges are induced in the channel by capacitor action

The induced positive charges make the channel less conductive and drain current decreases as  $V_{GS}$  is made more negative.

## N channel Depletion MOSFET



# Working



## **N channel Depletion MOSFET**

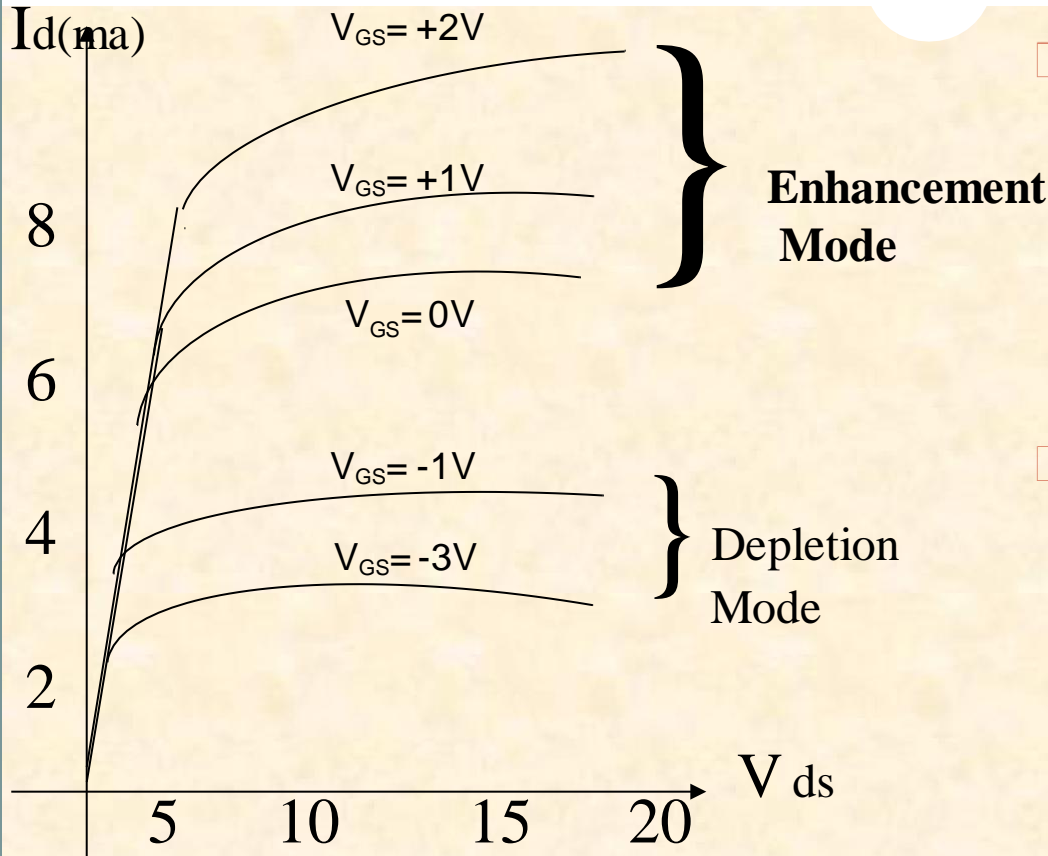
With negative voltage a depletion MOSFET behave like JFET.



□ When positive voltage is applied to the gate free electrons are Induced channel .

- This enhances the conductivity of the channel so increasing amount of current between terminals
- Since the action of negative voltage on gate is to deplete the channel of free n-type charge carriers so named as depletion MOSFET.

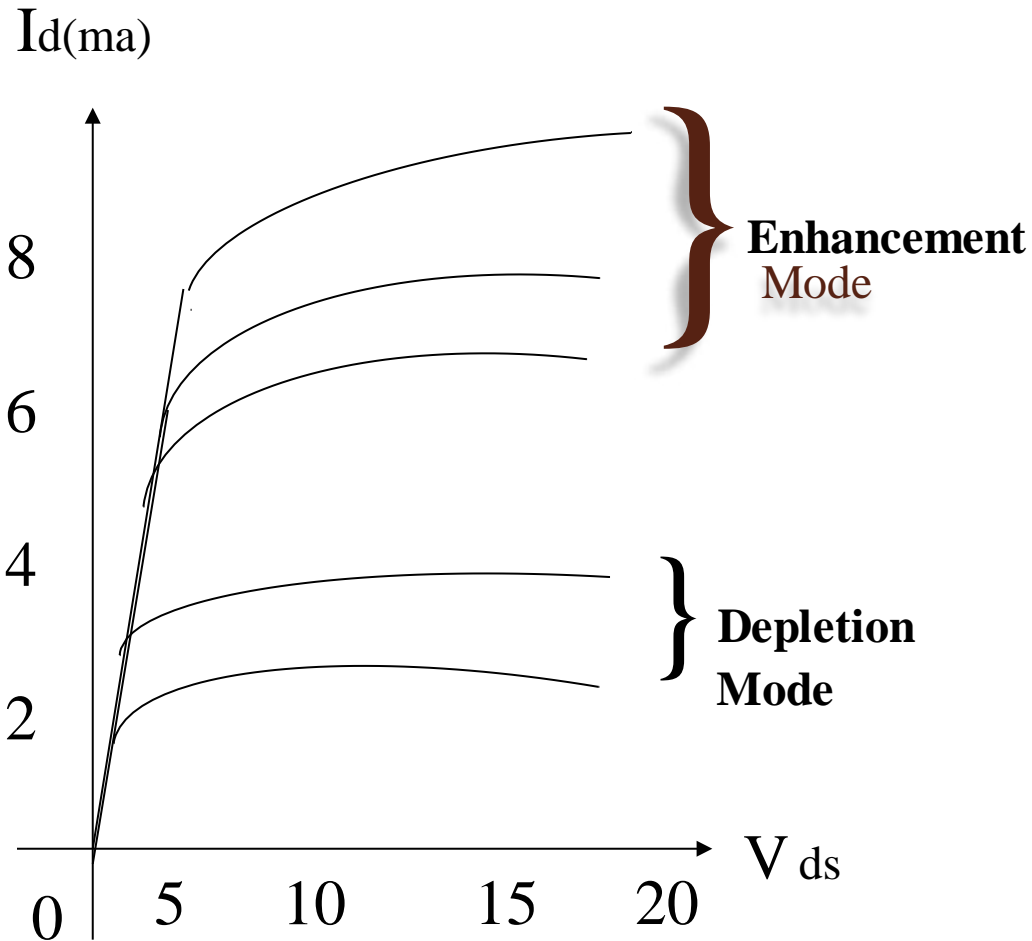
# Drain Characteristics of depletion MOSFET



□ When the gate source voltage is zero considerable drain current flows.

□ When the gate is applied with negative voltage, positive charge are induced in the n-channel through the  $\text{SiO}_2$  layer of the gate capacitor.

# Drain Characteristics of depletion MOSFET

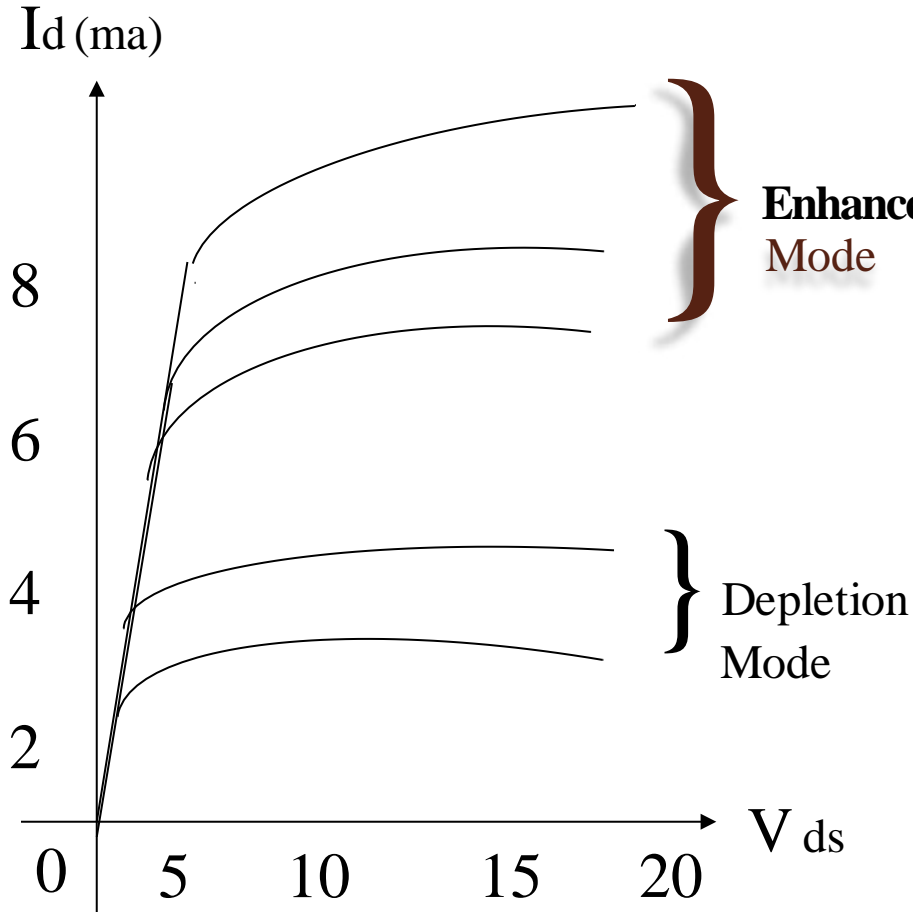


- The conduction in n-channel FET is due to electrons i.e., the majority carriers.

- Therefore the induced positive charges make the n-channel less conductive.

- The drain current therefore gets reduced with increase in the gate bias voltage.

# Drain Characteristics of depletion MOSFET

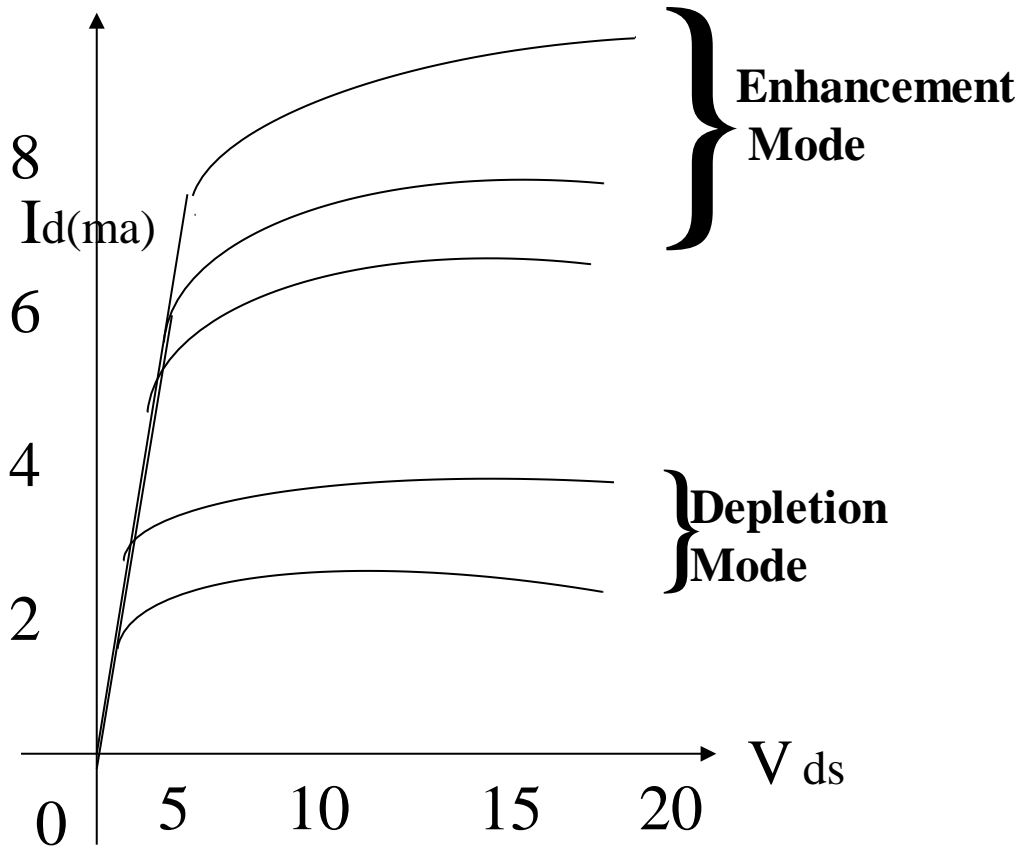


□ The distribution of charges in the channel results in depletion of majority carriers.

□ That is why this type of FET is called depletion MOSFET.

□ The voltage drop due to the drain current causes the channel region nearer to the drain to be more depleted than the region due to the source.

# Drain Characteristics of depletion MOSFET



- This is similar to the pinch off in JFET.



# Drain Characteristics of depletion MOSFET



- The depletion MOSFET can also be operated in enhancement mode simply by applying a positive voltage to the gate
- Application of positive gate voltage results in induced negative channel in the n-type channel

# Drain Characteristics of depletion MOSFET



Thus the conductivity of the channel gets increased the n-channel depletion MOSFET can be used as in enhancement mode by changing the gate voltage polarity.

- When a MOSFET is operated this way, we can it as dual mode MOSFET.

## Comparison of MOSFET and JFET

Sno	JFET	MOSFET
1.	JFET Gate is not insulated from the channel	MOSFET or IGFET is insulated from the channel
2.	Channel and gate form two pn junctions	Channel and gate form parallel plate capacitor.
3.	There are only 3 leads	There are 4 leads
4.	Can be operated in depletion mode only	Can be operated in both depletion and enhancement mode
5.	Input impedance is high	Input impedance is very high
6.	Signal handling capacity is less	Signal handling capacity is more
7.	Gate current is more	Gate current is very less Easy to fabricate, cheap. Most
8.	Fabrication is complex and costly	



## Advantages of MOSFET Over JFET



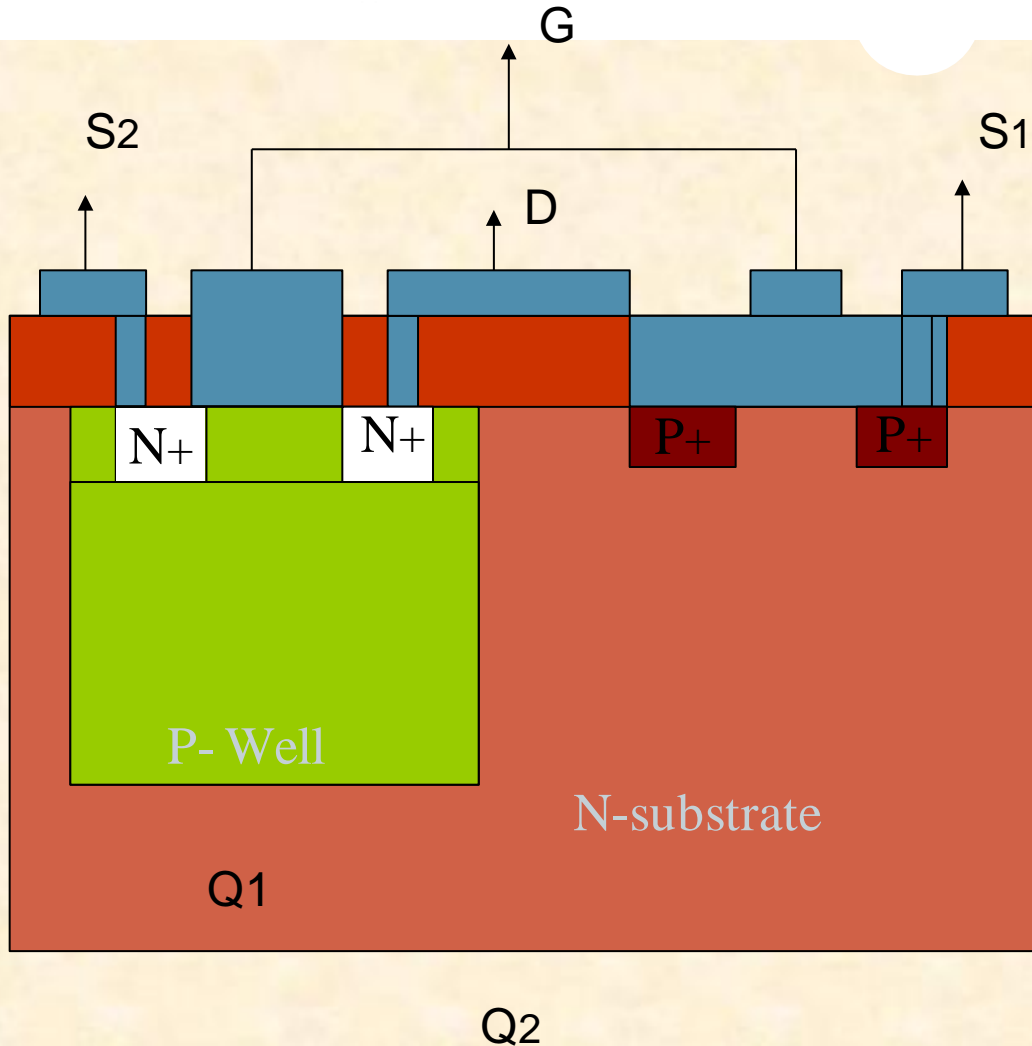
- The insulated gate in MOSFETs result in much greater input impedance than that of JFET
- Inter electrode capacitance are independent of bias voltage and these capacitances are smaller in case of MOSFETs than JFET.
- It is easier to fabricate MOSFET than JFET.
- MOSFET has no gate diode. This makes it possible to operate with +ve or -ve gate voltages



## Application of MOSFETs

- Because of higher input resistance ,the enhancement type MOS devices have been used as micro-resistor in integrated micro-circuits .
- For electrometer circuits where exceptionally low currents are to be measured MOSFETs are most nearly ideal.
- MOSFET s are very small in size .which make them suitable for highly complex digital arrays

# CONSTRUCTION OF COMPLEMENTARY MOSFET(CMOS)

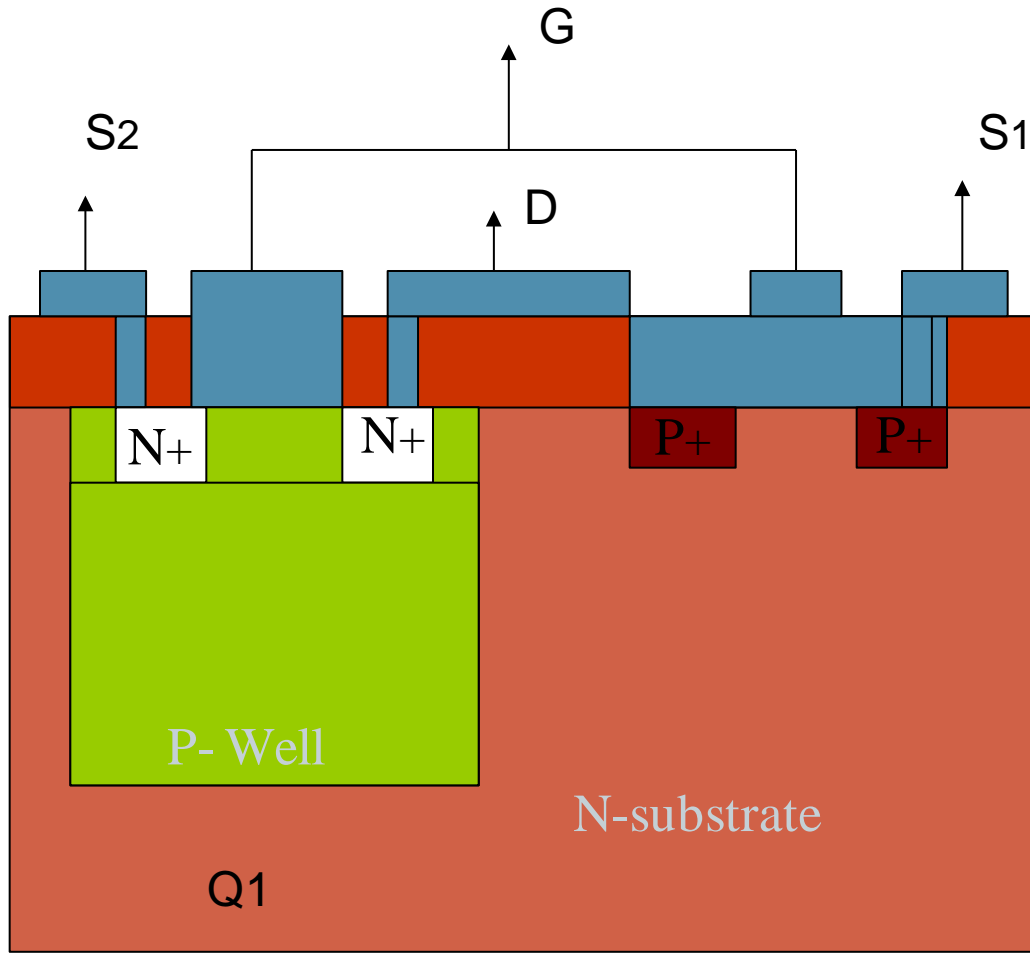


- In this device two MOSFETs that are complementary to each other are used.



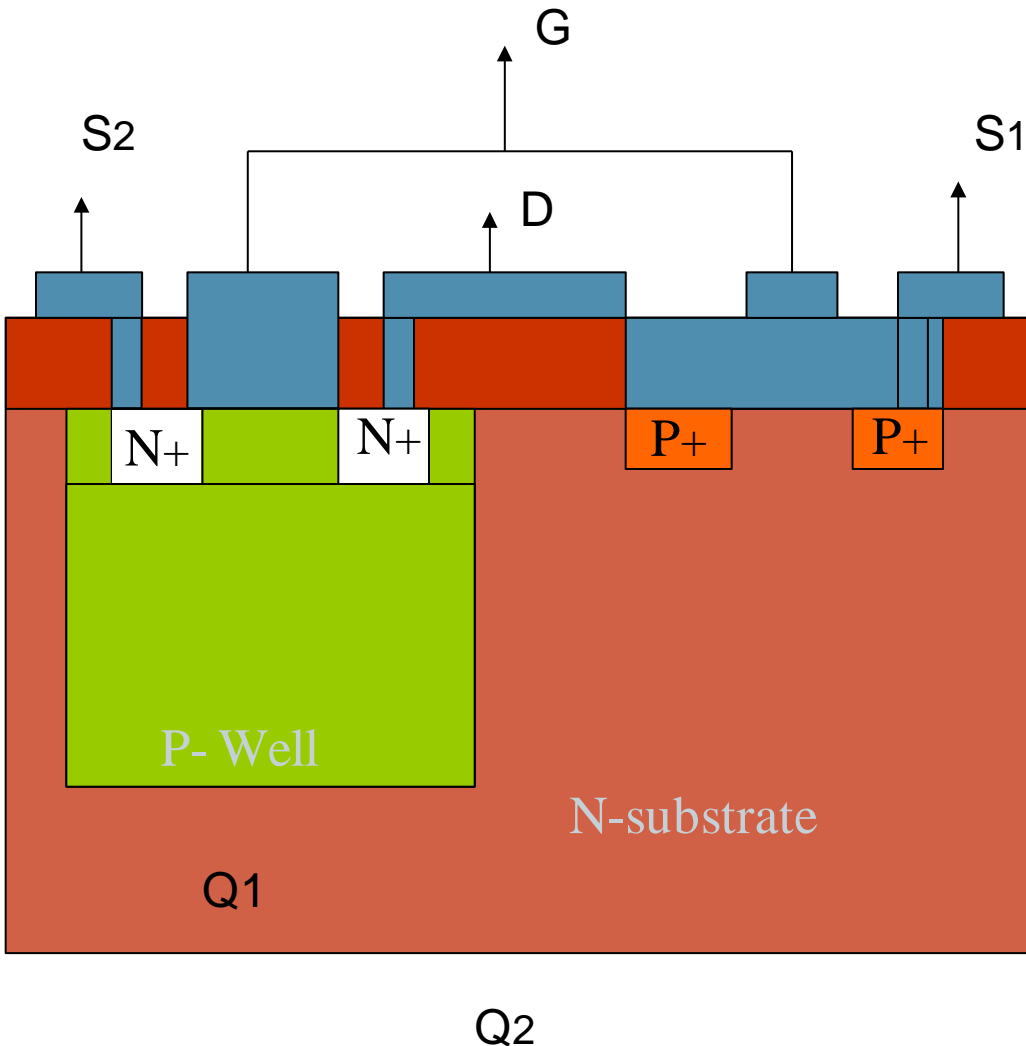


# CONSTRUCTION OF CMOSFET(contd.)



- The drains of both the MOSFETs are combined and single terminal is taken.

# CONSTRUCTION OF CMOSFET(contd..)



- Similarly the gates of both the transistors are combined and a single gate terminal is taken out.

- Here the input is applied at the input terminal  $v_i$ .





# WORKING PRINCIPLE OF CMOSFET



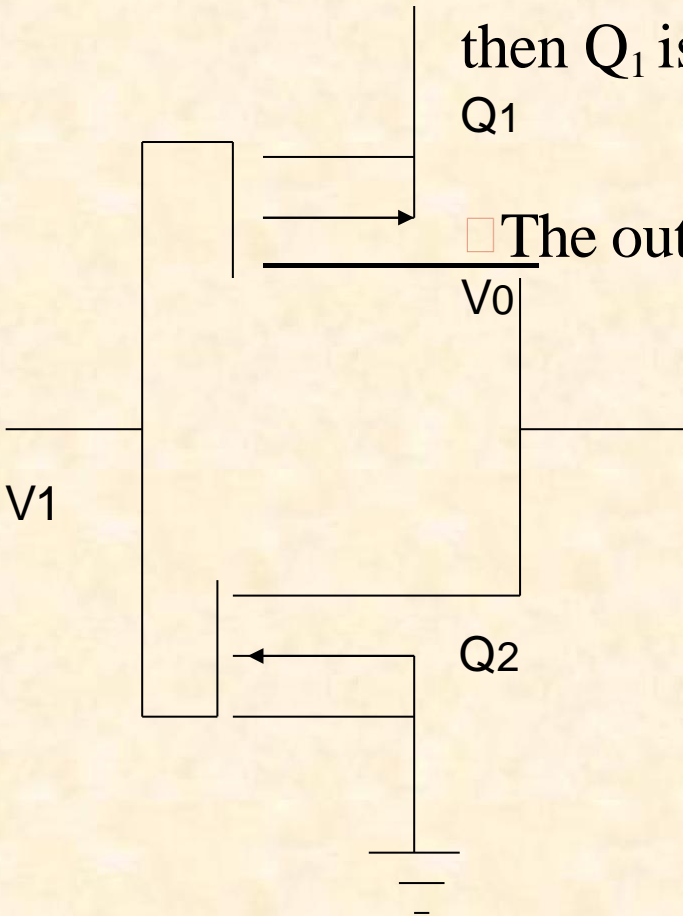
$-V_{DD}$

□ When  $v_i$  is high i.e., equal to  $-V_{DD}$  then  $Q_1$  is turned ON and  $Q_2$  is turned OFF.

$Q_1$

□ The output  $V_O$  is zero.

$V_O$

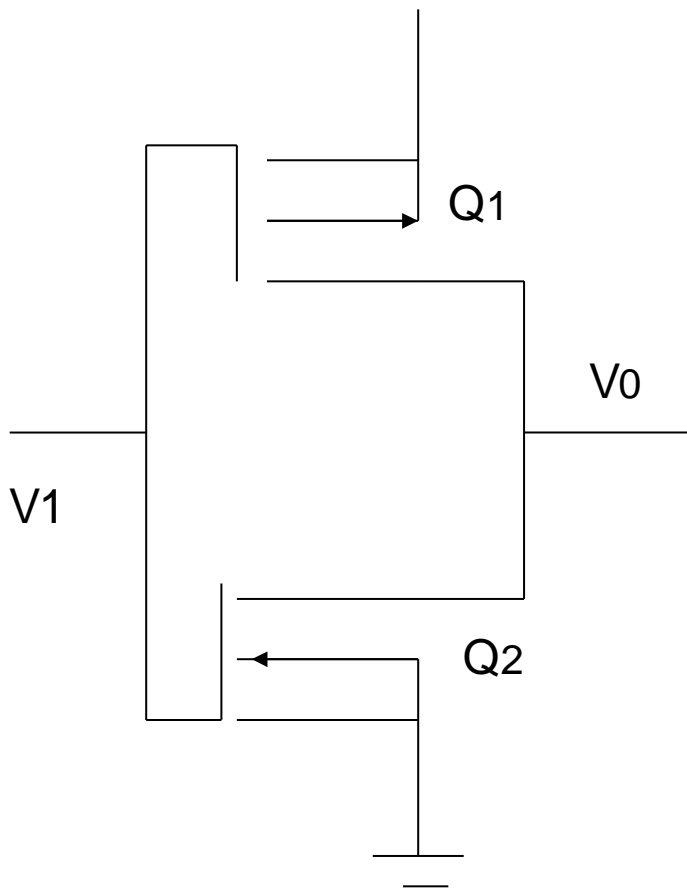


□ Similarly when the input voltage  $V_i$  is low i.e., equal to  $0v$ , the  $Q_2$  turned ON and  $Q_1$  turned OFF.

# WORKING PRINCIPLE OF CMOSFET(contd..)



-VDD

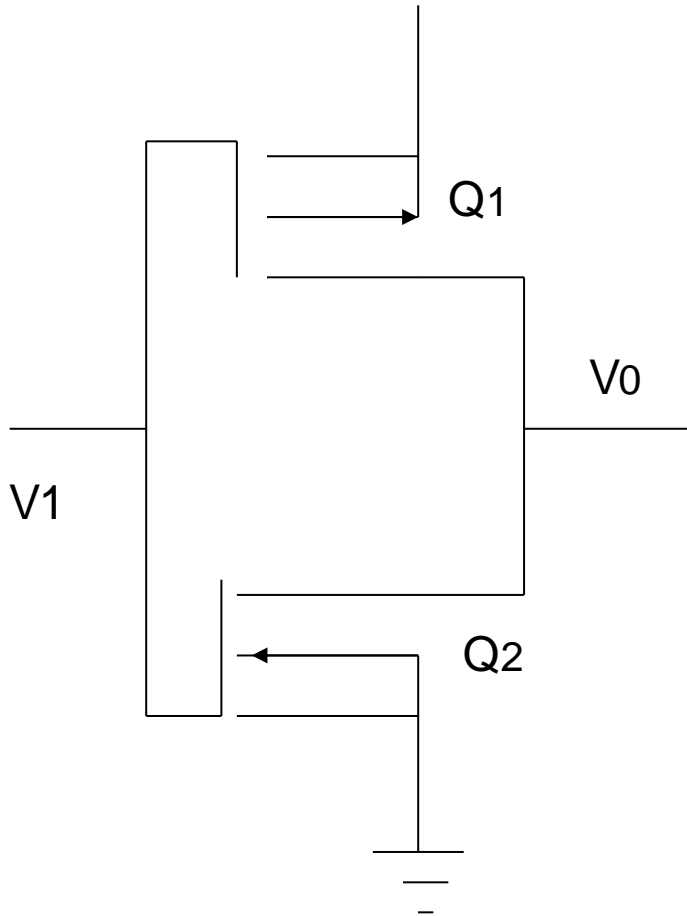


- So the output voltage  $V_0$  lies at  $-V_{dd}$  level i.e., high.

- Thus the CMOSFET in this configuration works as an inverter.



VDD



- The key advantage of using CMOS design is this extremely low power consumption usually of the order of  $50\text{mv}$

